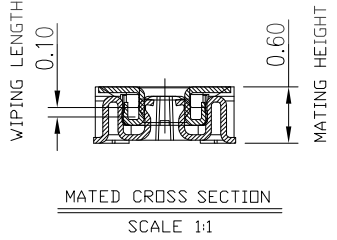
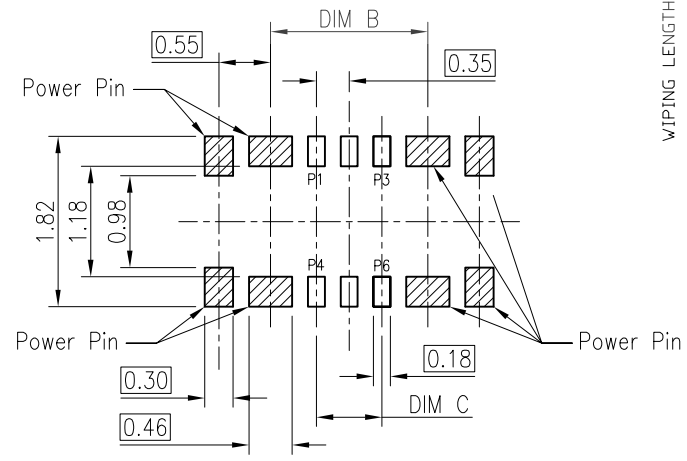
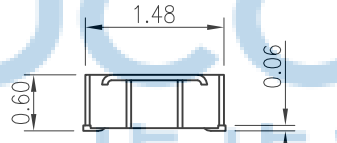
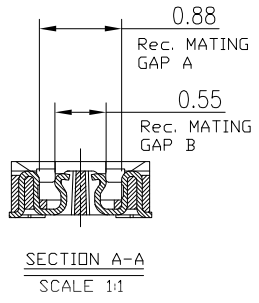
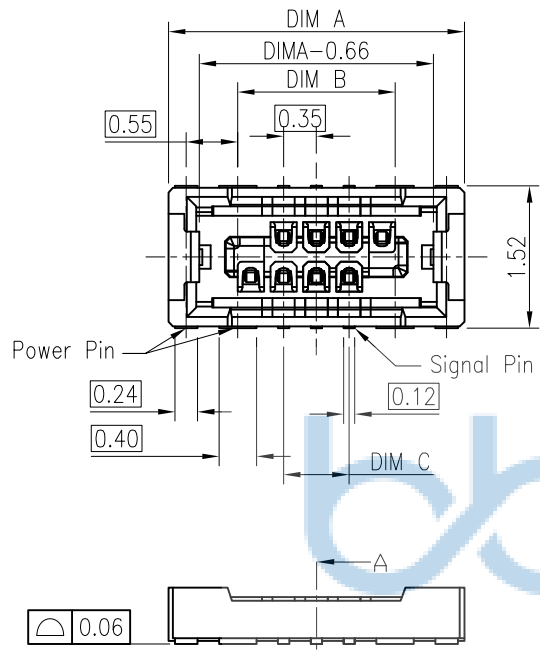
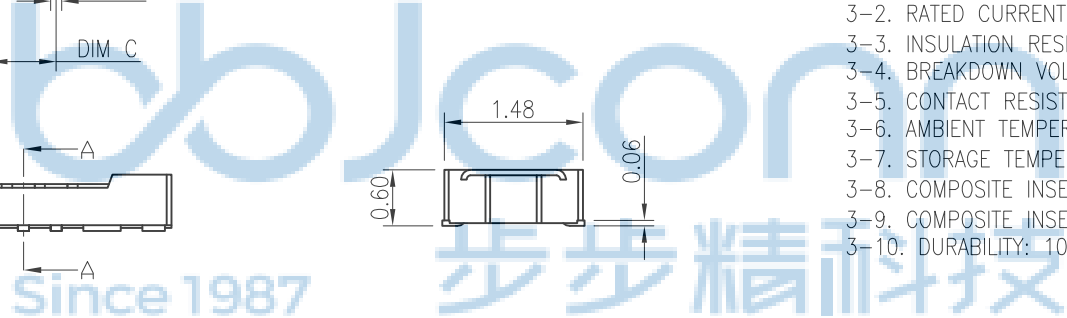
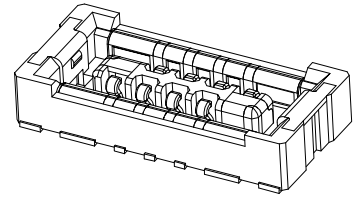


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



SPECIFICATIONS:

- 1) MATERIAL:
 - 1-1. HOUSING: LCP, BLACK (UL94 V-0)
 - 1-2. CONTACT: COPPER ALLOY
 - 1-3. CLIPS(POWER PIN): COPPER ALLOY
- 2) SURFACE TREATMENT:
 - 2-1. CONTACT: G/F PLATING ON CONTACT AREA
G/F PLATING ON SOLDER AREA
NI PLATING ALL OVER
 - 2-2. CLIPS: G/F PLATING ALL OVER
NI PLATING ALL OVER
- 3) CHARACTERISTICS:
 - 3-1. RATED VOLTAGE: 30V AC/DC
 - 3-2. RATED CURRENT: SIGNAL PIN 0.3A/PIN; POWER PIN: 3A Max.
 - 3-3. INSULATION RESISTANCE: 100MΩ Min.(INITIAL)
 - 3-4. BREAKDOWN VOLTAGE: 150V AC FOR 1 MIN, ELECTRICAL LEAKAGE ≤ 1mA
 - 3-5. CONTACT RESISTANCE: 70mΩ Max./SIGNAL PIN ; 20mΩ Max./POWER PIN
 - 3-6. AMBIENT TEMPERATURE: -40°C ~ +85°C
 - 3-7. STORAGE TEMPERATURE: -40°C ~ +50°C (PRODUCT ONLY)
 - 3-8. COMPOSITE INSERTION FORCE: 1.5*(M+4) N Max.(M=PIN NO.)
 - 3-9. COMPOSITE INSERTION FORCE: 0.15*M N Min. (M=PIN NO.)
 - 3-10. DURABILITY: 10 TIMES



Signal Pin No.	DIM A	DIM B	DIM C
6	3.16	1.68	0.70
10	3.86	2.38	1.40
14	4.56	3.08	2.10
24	6.31	4.83	3.85

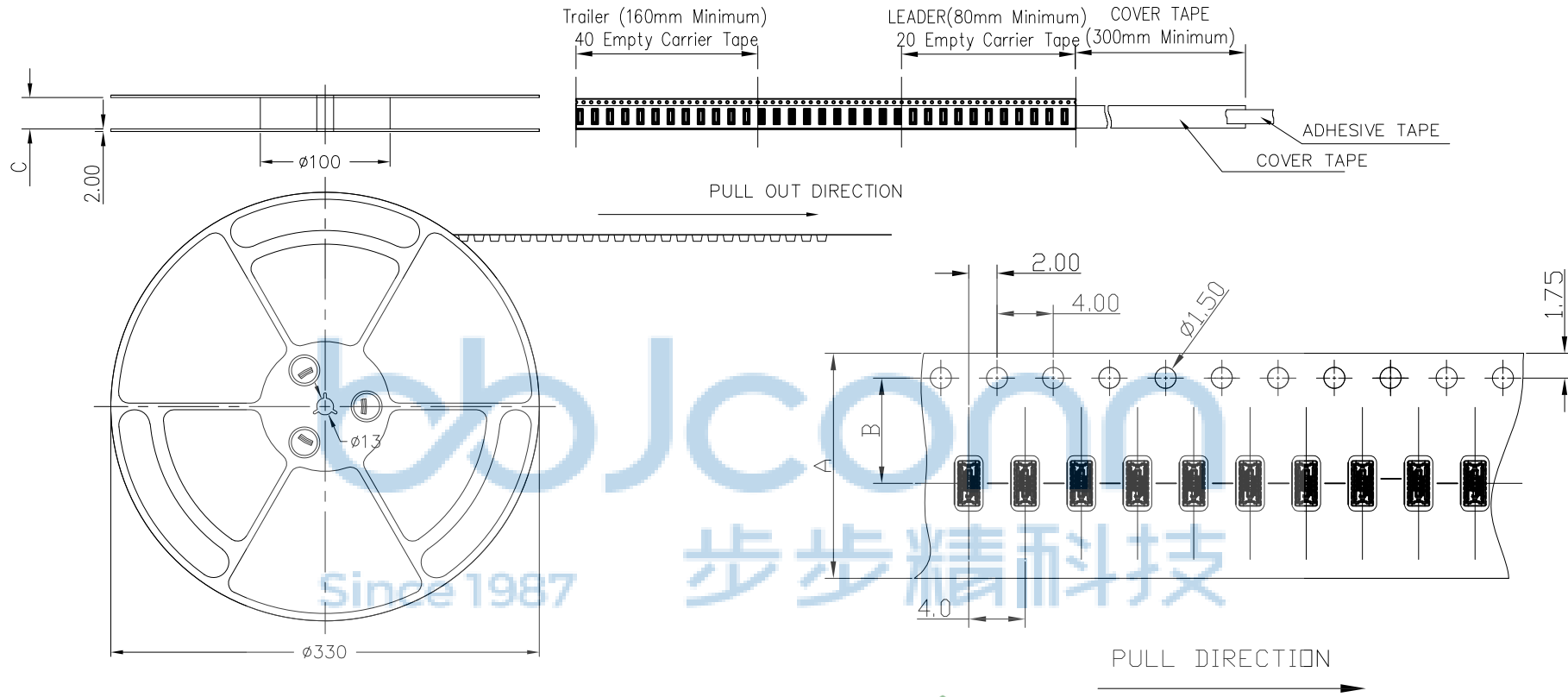
RECOMMENDED P.W.BOARD
TOLERANCE : ±0.03



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3' X'': ±2' X'X': ±1'	
APPD.	JM_Zheng	NAME: 板对板连接器 母座 0.35-6P 单槽SMT BCSTXX-0F2106K 编带	
CHKD.	LYX	PJ. NO.: WT.09.31-93-M002	
DR.	SGF	SIZE: A4 DRW NO.:	
PDWG.NO: 0484-1		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/3	

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

EMBOSSED TAPE PACKAGING



NOTE:

- 1.10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE $\pm 0.2\text{mm}$
- 2.CARRIER CAMBER IS WITHIN 1 mm IN 250mm.
- 3.MATERIAL : TRANSPARENT CONDUCTIVE POLYSTYRENE ALLOY.
- 4.THICKNESS : $0.3\pm 0.05\text{mm}$.
- 5.COMPONENT LOAD PER 13" REEL : 15000 PCS

TABLE:

06	16.00	7.50	17.4	15000
10	16.00	7.50	17.4	15000
14	16.00	7.50	17.4	15000
24	16.00	7.50	17.4	15000
NUMBER OF CONTACTS	A	B	C	QTY/REEL



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APPD.	JM_Zheng	P.J. NO.: WT.09.31-93-M002 SIZE: A4 DRW NO.:		FINISH: SEE NOTES MAT'L.: SEE NOTES	
CHKD.	LYX	SCALE: N/A		REV.: A0	UNIT: mm
PDWG.NO:	0484-1	DR.	SGF	PAGE: 2/3	

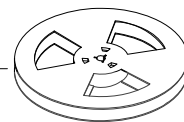
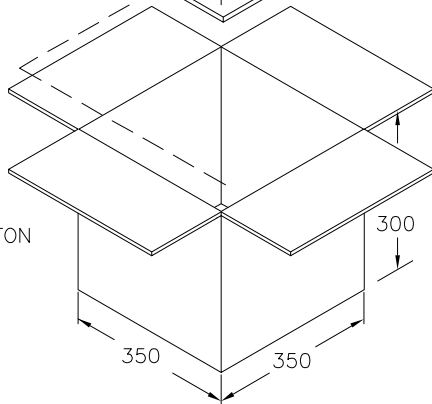
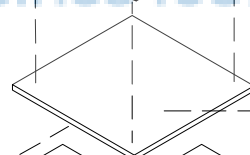
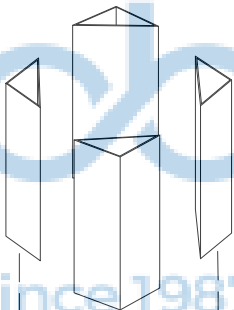
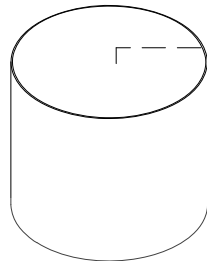
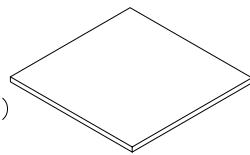
紙板(上)
PASTEBOARD(UPPER)
(2)

塑膠袋
PLASTIC BAG
(4)

三角隔板
TRIANGLE PARTITION
(3)

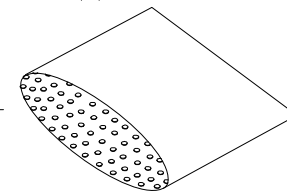
紙板(下)
PASTEBOARD(LOWER)
(2)

外箱
CARTON
(1)



TAPE & REEL
(5)

氣泡袋
BUBBLE BAG
(6)



	(1) 外箱	(2) 紙板	(3) 三角隔板	(4) 塑膠袋	(5) 塑膠圓盤	(6) 氣泡袋	最小包裝量 (PCS)
BCST06-0F2106K	1	2	4	1	10	10	15000
BCST10-0F2106K	1	2	4	1	10	10	
BCST14-0F2106K	1	2	4	1	10	10	
BCST24-0F2106K	1	2	4	1	10	10	



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PDWG.NO: 0484-1		DR. SGF					